What is claimed is:

1. A heat-curable adhesive composition comprising:
an ethylene-glycidyl (meth)acrylate copolymer;
a low density polyethylene;
an ethylene-α-olefin copolymer; and
a heat curing agent for said ethylene-glycidyl (meth)acrylate copolymer.

2. A heat-curable adhesive composition of claim 1, wherein the minimum density of said low density polyethylene is 0.910 as measured according to ASTM D1248-84.

3. A heat-curable adhesive composition of any preceding claim, wherein the maximum density of said low density polyethylene is 0.925 as measured according to ASTM D1248-84.

4. A heat-curable adhesive composition of any preceding claim, wherein, in said ethylene-α-olefin copolymer, the polymerization ratio of ethylene to α-olefin is 90:10 to 10:90.

5. A heat curable adhesive composition of any preceding claim, wherein the minimum density of said ethylene-α-olefin copolymer is 0.850 as measured according to ASTM D1248-84.

6. A heat curable adhesive composition of any preceding claim, wherein the maximum density of said ethylene-α-olefin copolymer is 0.909 as measured according to ASTM D1248-84.

7. A heat-curable adhesive composition of any preceding claim, wherein said heat curing agent is a rosin having a carboxyl group in the molecule.

8. A heat-curable adhesive composition of any preceding claim, wherein said composition is in the form of a thin film of 5 to 80 μm in thickness.

9. A heat-curable adhesive composition of any preceding claim, wherein, after post-curing, the composition has a dielectric constant of 2.5 or less, and a dielectric loss tangent of about 0.015 or less when measured at the

frequency of about 1 GHz.